Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L30	2	US-6031723-\$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:32
L31	7	US-6051093-\$.DID. OR US-5808873-\$.DID. OR US-6163456-\$.DID. OR US-6531022-\$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:34
L32	11	US-6184577-\$:DID: OR US-5401688-\$:DID: OR US-4751126-\$:DID: OR US-6038133-\$:DID: OR US-6338767-\$:DID: OR US-5018051-\$:DID:	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:42
L33	2	US-6404052-\$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:42
L34	11	("5434452" "5488542" "5789271" "5821626" "5877559" "5995379" "6124634" "6157084" "6211576" "6242103").PN. OR ("6404052").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 14:07
L35	2	"6417060".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:10
L36	82	electrodes adj making and 29/\$. ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:16
L37	0	electrodes adj matching near method and 29/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/01/11 14:17
L38	1	electrodes adj sandwich near separation	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:24
L39	947	electrodes adj sandwich	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:24
L40	16	electrodes adj sandwich and 29/\$. ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:31

L41	2	"6680441".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:31
L42	9	("5161093" "5336928" "6180881" "6239496" "6292366" "6359235" "6404643" "6469374" "6512182").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 14:35
L43	50	pcb and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:36
L44	6	pcb and embedded near component and 29/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:37
L45	7	pcb and embedded near component and (29/832, 174/260 , 174/262 , 29/825 , 29/830 , 29/852 , 361/330 , 361/760).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/01/11 15:05
L46	50	pcb and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L47	0	pcb and resin near film and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L48	19	resin near film and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L49	11	("20020076919" "20020119396" "20030038373" "20030075811" "5353195" "5872051" "5874770" "6038133" "6570469" "6576499" "6784765").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 15:11
L50	6535	electrodes near making	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:12
L51	416	electrodes near making and "438"/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:12
L52	318	electrodes near making and "29"/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:29

L53	132	minh near trinh.xp.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:40
L54	2	"6038133".pn.	EPO; JPO; DERWENT; IBM_TDB	OR		2006/01/11 15:40